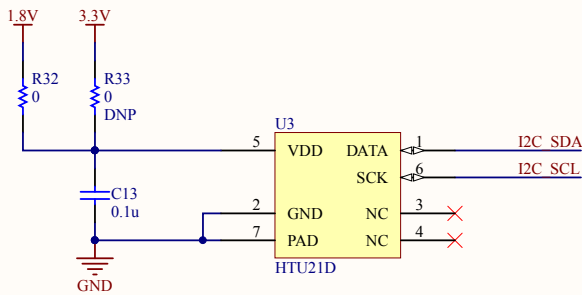
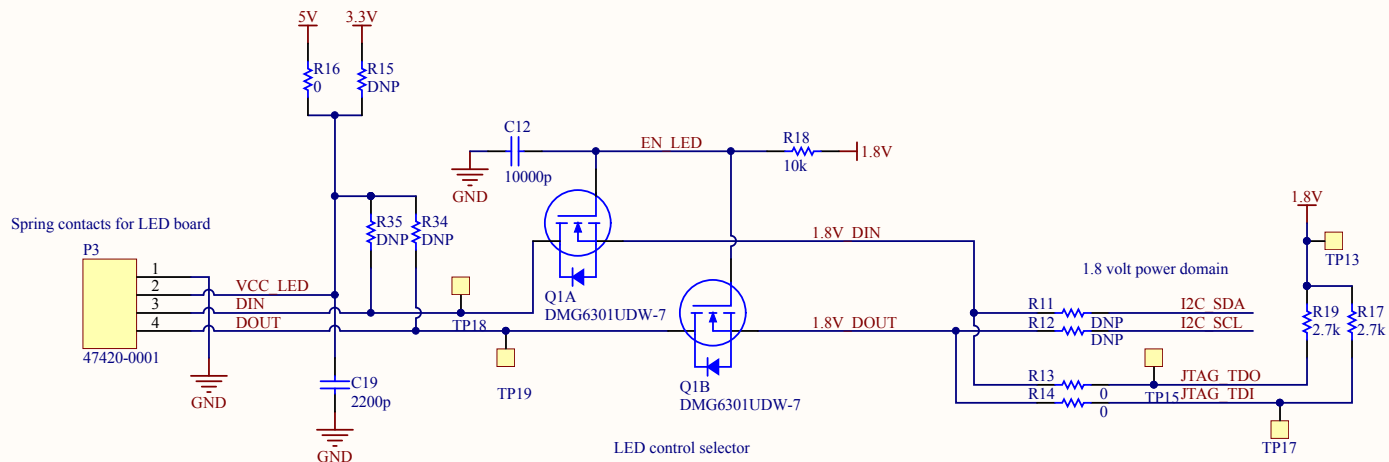


Supply needs to be 1.8V when I2C is pulled up to 1.8V. VIH for HTU21D is .7Vdd

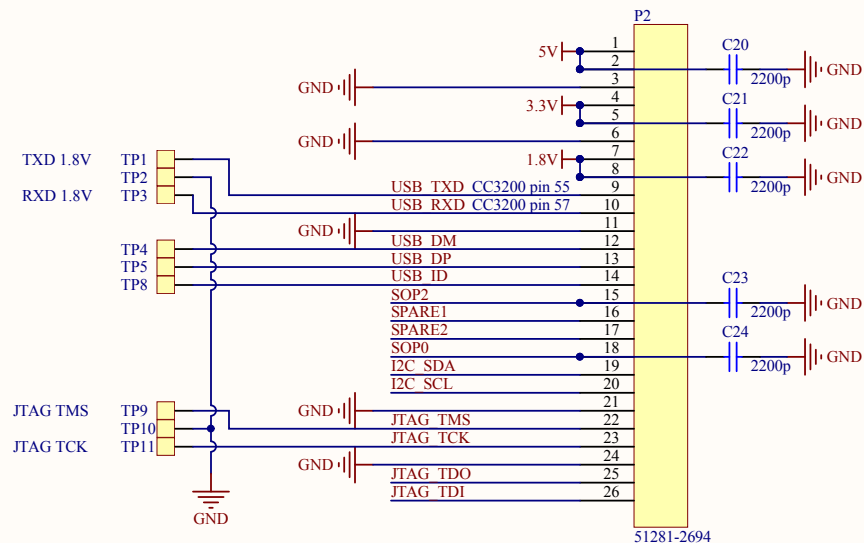
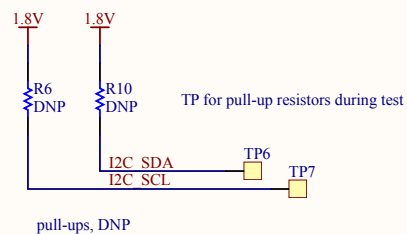


Hello

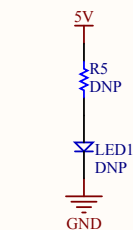
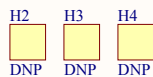
TITLE		REV
Temperature / Humidity		PVT
DATE	DRAWN BY	SHEET 2 OF 3
12/30/2014	D. Fusi	



connector to the middle board



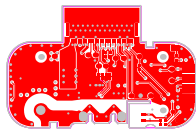
mounting holes. H1 has been replaced with a via

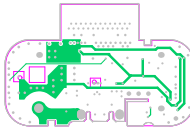
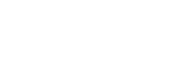
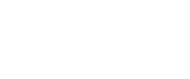


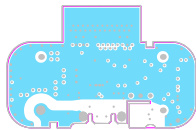
USB_ID used to assert SOP2
to program Code Flash
thru CC3200 Boot Rom UART

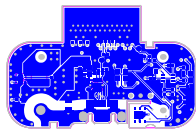
Hello

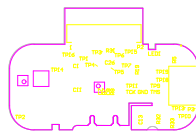
TITLE Morpheus_bottom		REV PVT
DATE 12/30/2014	DRAWN BY D. Fusi	SHEET 3 OF 3

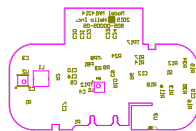


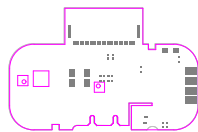


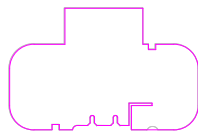


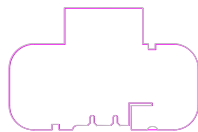


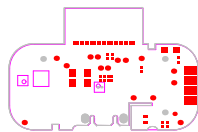


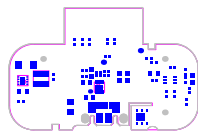


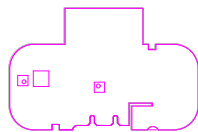










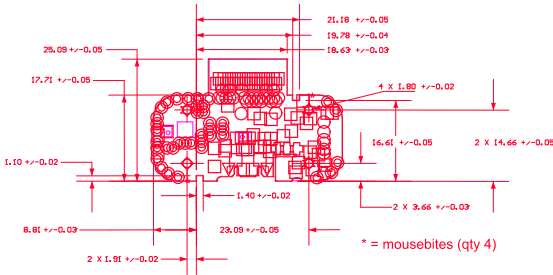



Fabrication / Assembly Notes

1. Material: Rigid FR-4, RoHS compliant; material should meet or exceed requirements of IPC 4101/126. ITEG IT-180A Pre-approved.
2. Number of electrical layers: 4
3. Trace / Space minimum: 5mil (all layers)
4. Thickness: .97mm +/- 0.1mm (finished)
5. Finish: ENIG plating on exposed copper
6. Soldermask: per IPC-SM-840, color matte black registration within +/- 76um of circuit layer
7. Silkscreen: use white silkscreen on top and bottom layers. Clip on pads.
8. RoHS: parts shall be RoHS compliant as per European Union directive 2002/95/EC
9. Board must be lead free process compatible and able to withstand minimum of 5 cycles at 250 degrees celsius
10. All Test/QA/QC markings to be made on back side of PCB
11. x mousebites shall be no larger than 0.05 mm
12. All Dimensions are after plating/finishing
13. All components must be placed within +/- 0.10mm

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Paste				
2	Top Overlay				
3	Top Solder	Solder Resist	0.010mm	3.5	
4	Top Layer	Copper	0.036mm		
5	Dielectric1	FR-4	0.254mm	4.2	
6	GND	Copper	0.036mm		
7	Dielectric2	FR-4	0.330mm	4.2	
8	Plar	Copper	0.036mm		
9	Dielectric3	FR-4	0.254mm	4.2	
10	Bottom Layer	Copper	0.036mm		
11	Bottom Solder	Solder Resist	0.010mm	3.5	
12	Bottom Overlay				
13	Bottom Paste				

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
◊	1	1.800mm <70.87mil>	PTH	Round
▽	2	0.600mm <23.62mil>	PTH	Slot
◊	3	1.800mm <70.87mil>	NPTH	Round
◊	4	0.700mm <27.56mil>	PTH	Round
◊	32	0.305mm <12.00mil>	PTH	Round
●	38	0.400mm <15.75mil>	PTH	Round
□	73	0.200mm <7.87mil>	PTH	Round
153 Total				



METRIC		DRAWN	DATE		
DIMENSIONS ARE IN MILLIMETERS		DESIGNER	DATE		
TOLERANCES:		dfusi / rsb/ ben	12/30/2014	TITLE:	
0 > - < 2 0.10		PROPRIETARY AND CONFIDENTIAL THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF HELLO INC.		Morpheus Bottom Board	
2 > - < 10 0.10					
10 > - < 50 0.10					
50 > - < 100 0.15					
100 > - < 200 0.20					
200 > - 0.20		ANY REPRODUCTION IN PART OR AS A WHOLE, WITHOUT THE WRITTEN PERMISSION OF HELLO INC IS PROHIBITED.		SIZE	DWG. NO.
ANGLES 1.00				B	201-00005-05
				SCALE: 2:1	WEIGHT:
				SHEET 1 OF 1	

